Electronic Supplementary Material (ESI) for Nanoscale.

Electronic supplementary information

Hollow silica-copper-carbon anodes using copper metal-organic frameworks as skeletons

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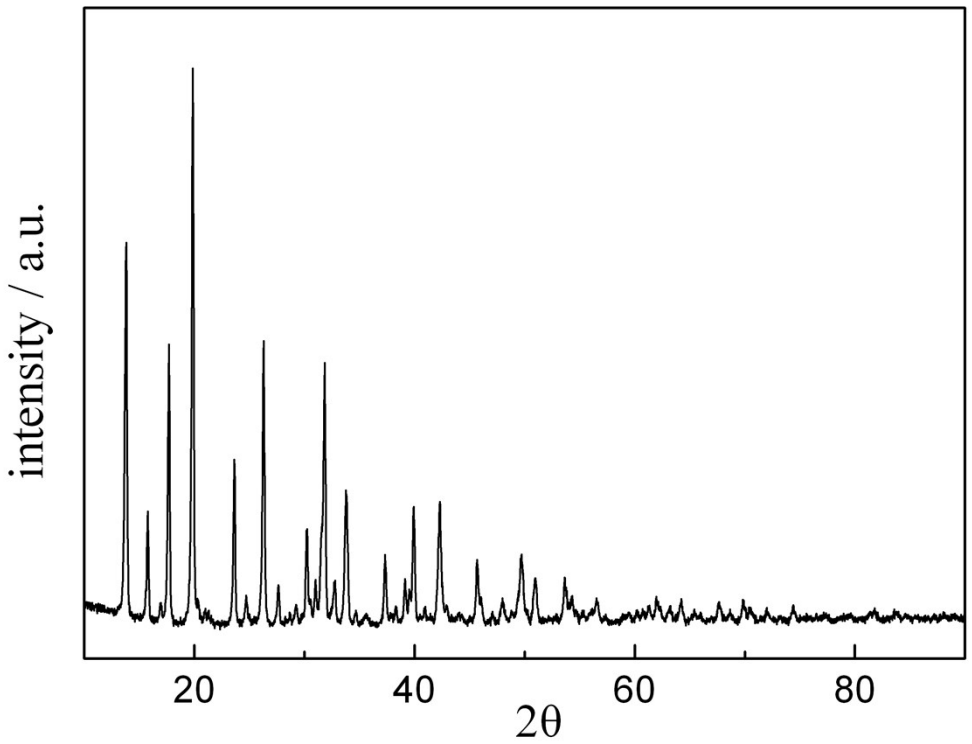

Fig. S1 XRD patterns of as-synthesized Cu-MOF template.

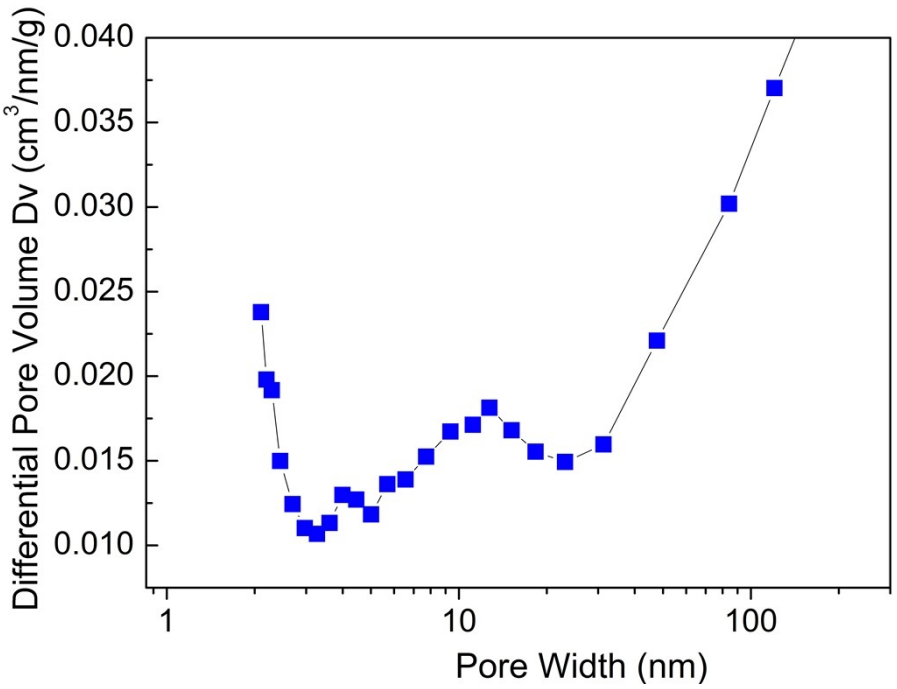

Fig. S2 pore size distribution of the H-SCC composite.

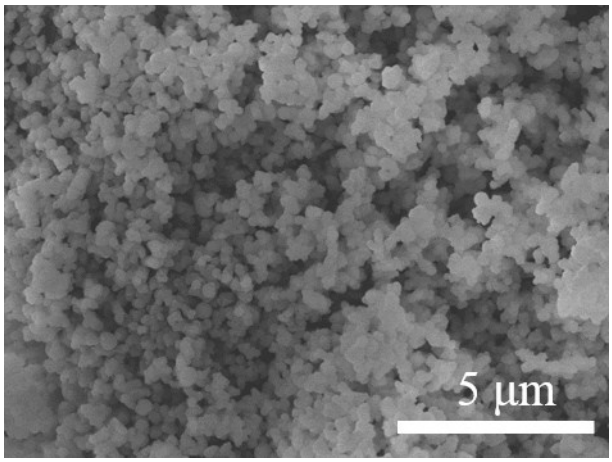

Fig. S3 Low-magnified FESEM image of products obtained after heating Cu-MOF@SiO_2 at 700 ℃.

Table. S1 the content of C, O, Si, Cu by the EDX.

Element	C (K)	O (K)	Si (K)	Cu (K)
Weight %	2.43	48.44	33.24	15.87
Atomic %	4.34	64.91	25.38	5.35

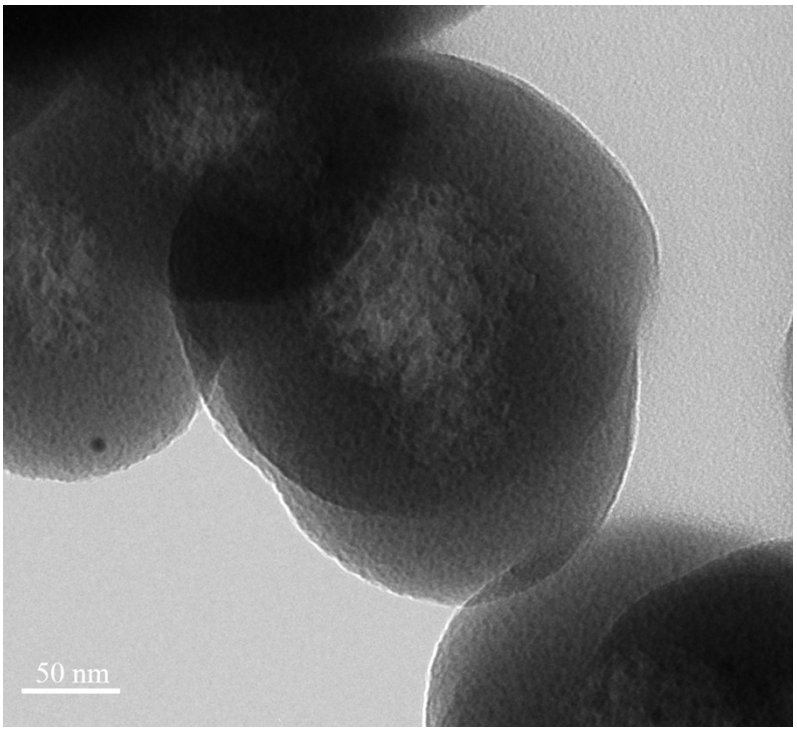

Fig. S4 higher resolution TEM image of the H-SCC nanocomposite.

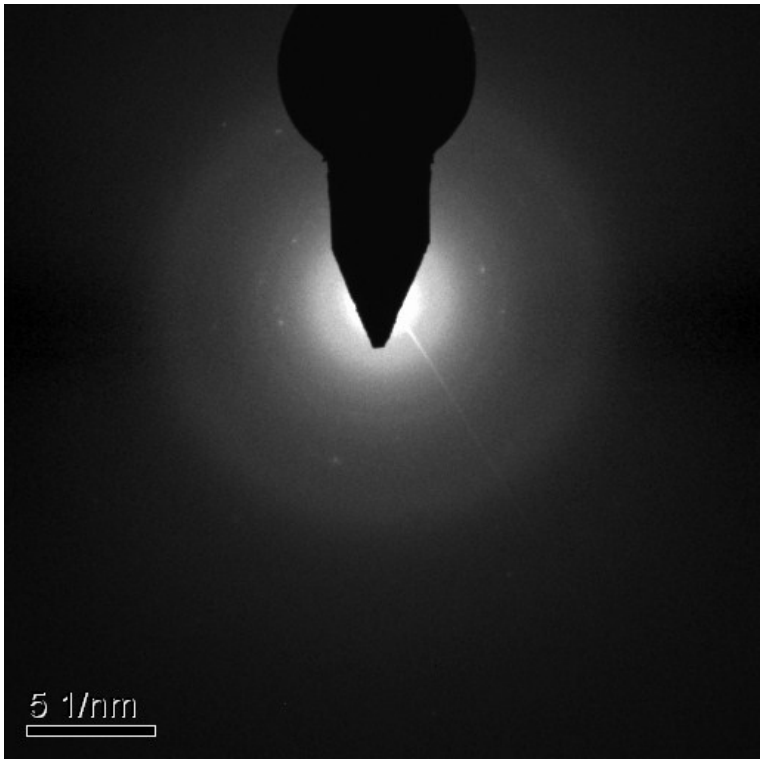

Fig. S5 the SAED pattern of the H-SCC composite.

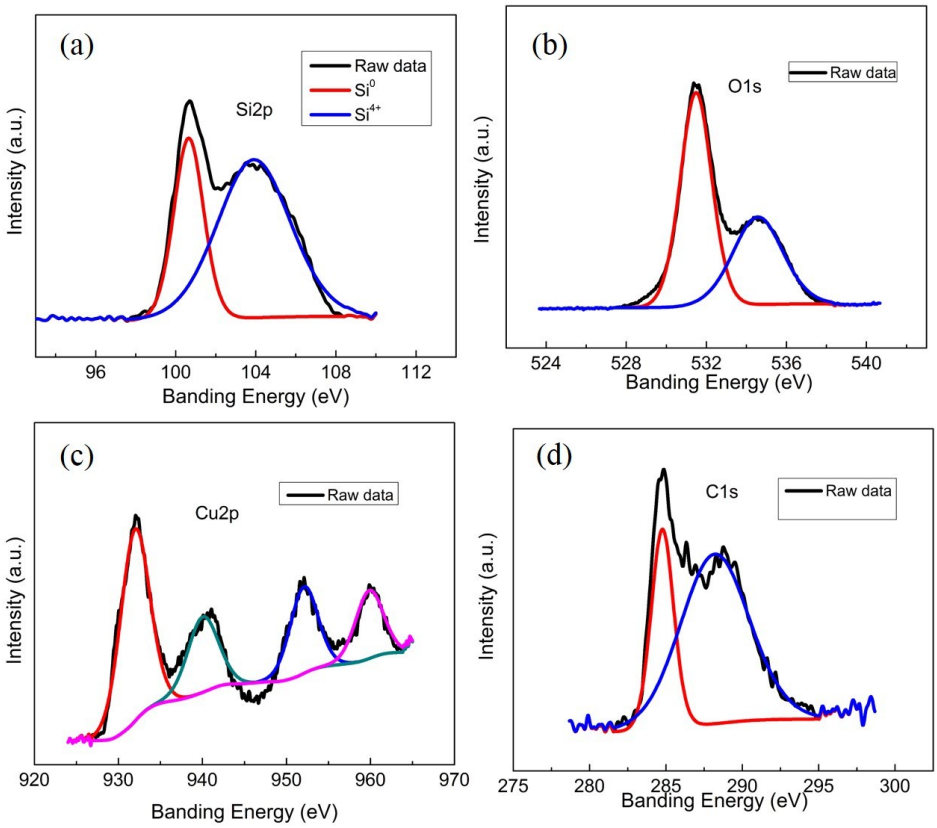

Fig. S6 XPS spectra for the H-SCC composite: (a) Si 2p; (b) O 1s; (c) Cu 2p; and (d) C1s.